



Rota Solder

There are requirements to tin components in solder pot to give protection or to have good solder ability. One always faces a problem of accumulating dross caused by flux ingress on the solder surface. Operator has to repeatedly take out accumulated dross. This increases solder wastage, increases effective cycle time and poor quality of tin layer formation on the tinned leads.

Model No.	RS125LF
Pot Dimensions	125 X 50 mm
Wattage	700 W
Solder Capacity	5.5 Kg
Temp. Range	200° C to 450° C

To overcome this we have introduced a rotary solder pot. This system is having a rotating solder pot with a wiper that skims solder surface while pot is rotating offering a clean dross free surface. This wiper is so arranged that accumulated dross progresses towards outer rim of solder pot and is collected in a collector provided. This completely eliminates operator intervention to clean the pot as has to be done earlier.

This system is available in one model RS125LF. Temperature can be set from 200° C to 450° C within $\pm 3^\circ$ C. At 250° C one can carry out normal tinning operations for 60:40 solder. One can solder wound components having self-solderable wires at 380° C. This pot can be used with lead free solder also.

This system can be placed on the tabletop or can be accommodated in line with any other production equipment. We can offer any other sizes as per requirement or for a particular job.

